

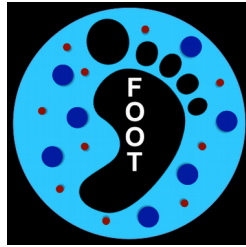


Status of MSD subsystem

L. Servoli, B. Alpat, G. Ambrosi, S. Bizzaglia, M. Caprai, E. Fiandrini,
M. Ionica, K. Kanxheri, F. Moscatelli, P. Placidi, G. Silvestre

FOOT Collaboration Meeting
Bologna, 4-5 dicembre 2017

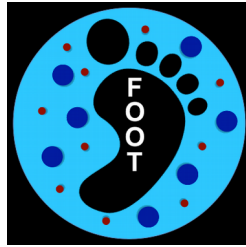
L. Servoli – Bologna 2017/12/5



1) Hardware activities

2) First results from july 2017 LNS beam test on LGAD

3) First results from july 2017 LNS beam test on NON
LGAD Microstrips

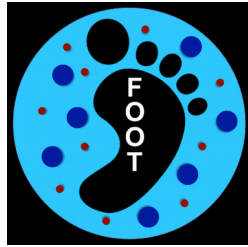


Hardware activities: LGAD

- 1) Received in July two structures from N. Cartiglia (1x1 mm) to start learning their response. Used in July beam test @ LNS (more later)
- 2) Received 6 square structures in September, 5.6x6.3 mm², with 30 microstrips each one, 150 μm pitch, 630 μm thickness.

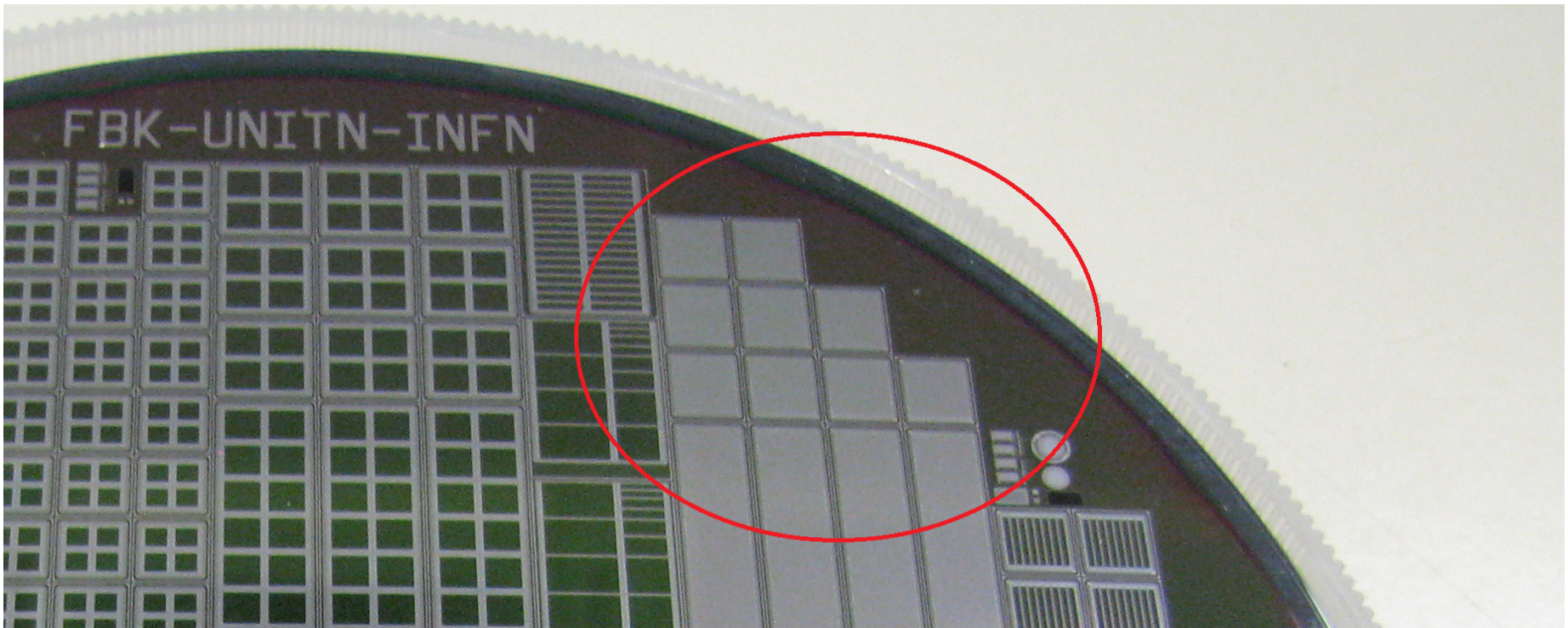
Hardware activities: NON LGAD

- 3) Received two devices 99 x 96 mm single side sensor, 150 μm thickness from Micron Semiconductor (UK)
- 4) Discussions going on with Hamamatsu concerning double sided 150 μm thick microstrip sensor.



Hardware activities: LGAD

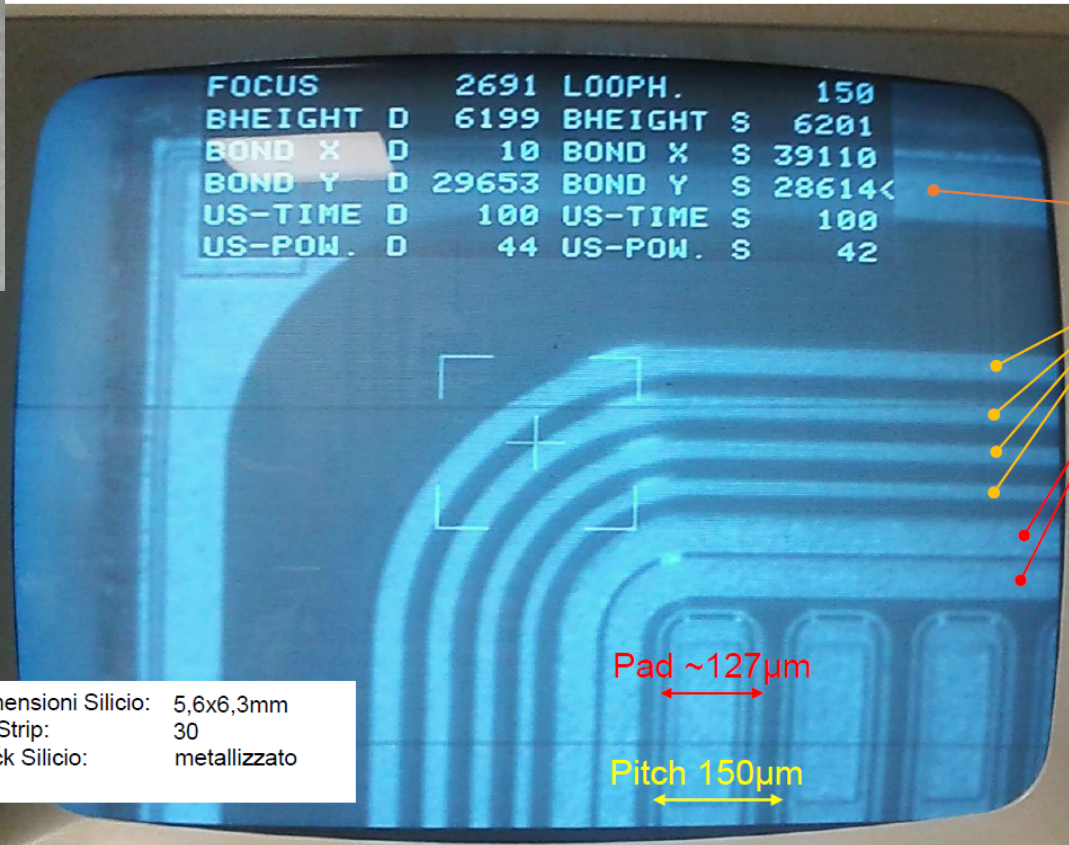
2) Received 6 square structures in september, $5.6 \times 6.3 \text{ mm}^2$, with 30 microstrips each one, $150 \mu\text{m}$ pitch, $630 \mu\text{m}$ thickness. Cut from MPW of Nicolò with FBK.





Hardware activities: LGAD

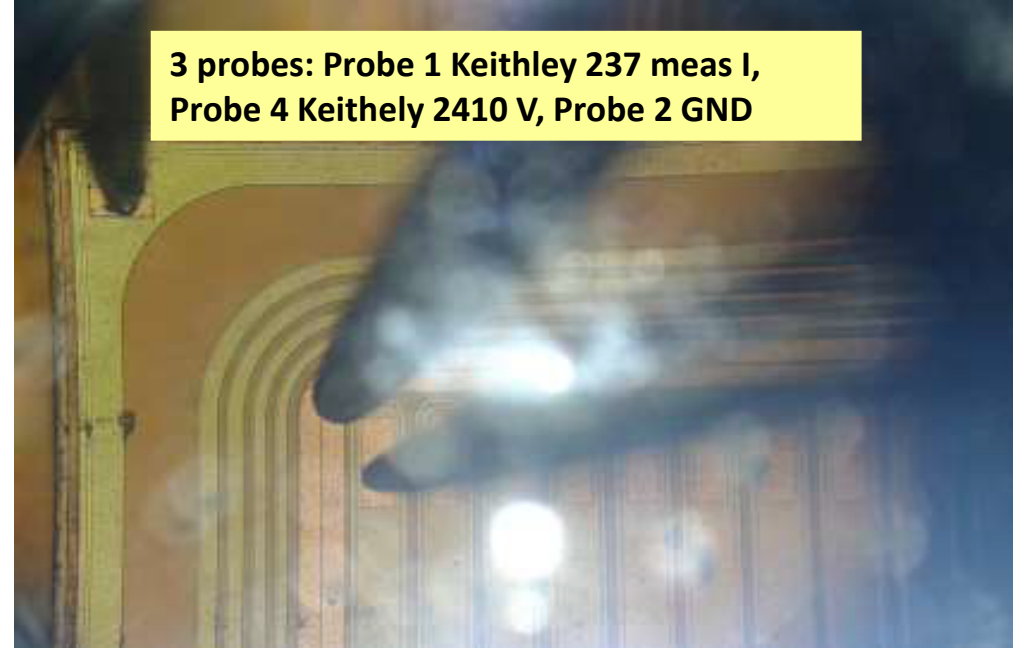
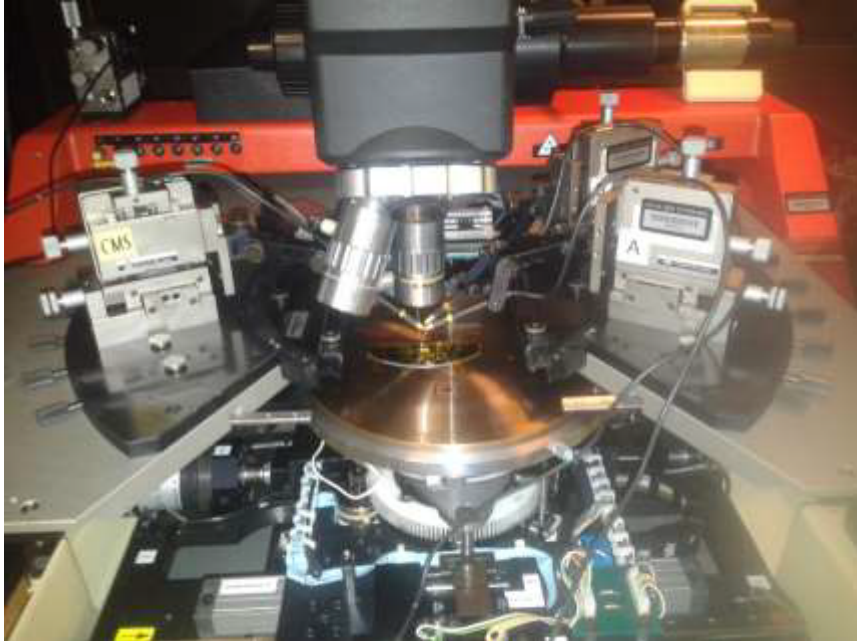
2) Received 6 square structures in september, $5.6 \times 6.3 \text{ mm}^2$, with 30 microstrips each one, $150 \mu\text{m}$ pitch, $630 \mu\text{m}$ thick.



Dimensioni Silicio: 5,6x6,3mm
N° Strip: 30
Back Silicio: metallizzato

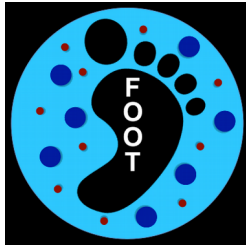
1 structure (NG)
with NO LGAD .

5 structures identical
(#1-5) WITH LGAD.

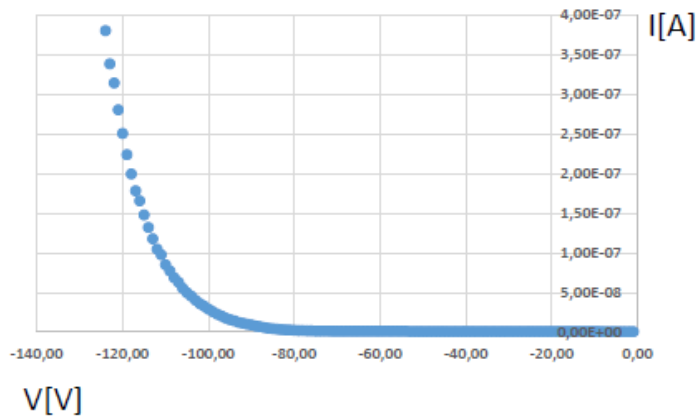


Test with probe station for IV measurement:

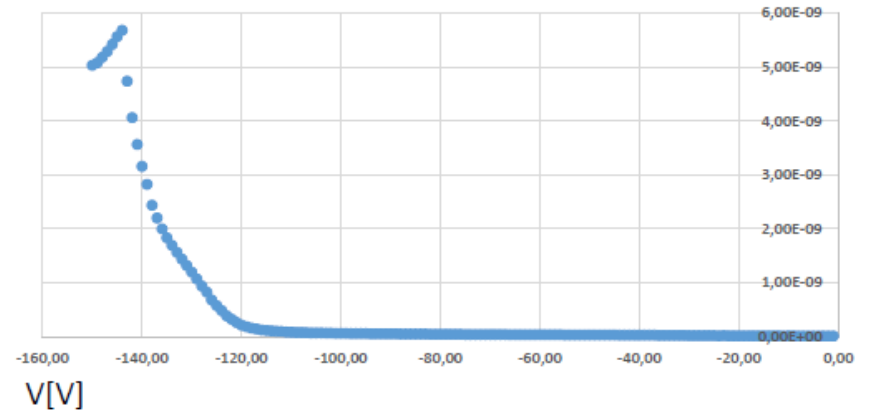
- For the $I_{\text{leak total}}$ with two probes: Negative bias on external BIAS ring, read current on the innermost guard ring;
- For the $I_{\text{single strip}}$ IV with 3 probes: Negative bias on external BIAS ring, GND on the innermost guard ring, read current on the strip.



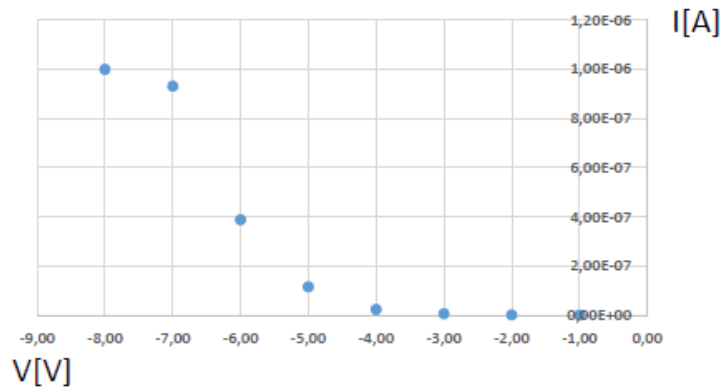
LGAD1



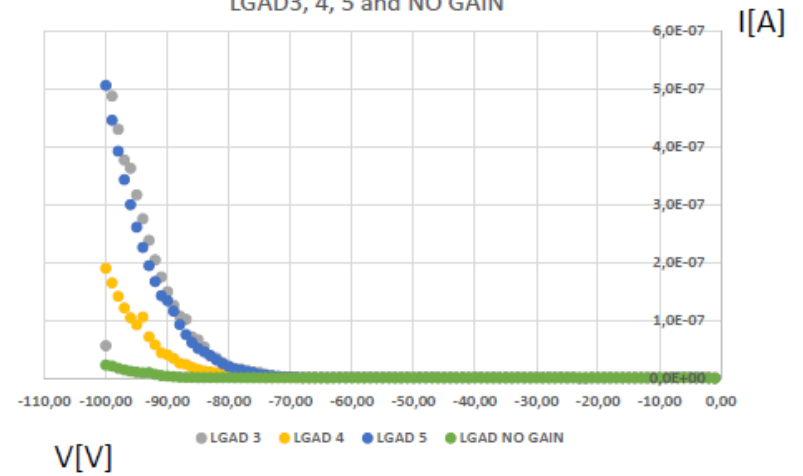
LGAD1 STRIP1

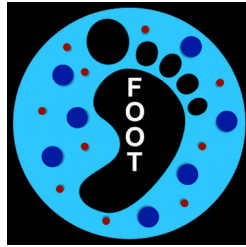


LGAD2



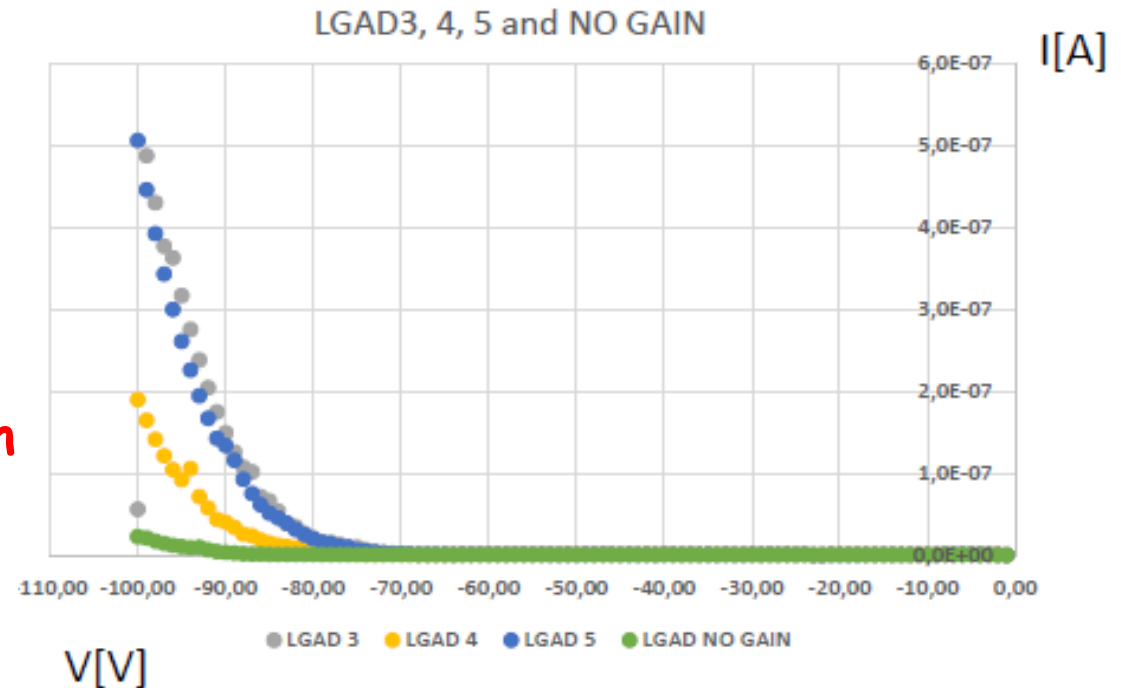
LGAD3, 4, 5 and NO GAIN





Summary:

- structure #1 low breakdown (80-90 V), **problems**
- structure #2 **probably broken**
- structure NG : low current expected behavior.
Checking the values.

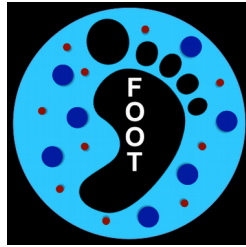


- structure # 3 and 5: expected behaviour. **Good.**
- structure # 4: intermediate current. **Checking**



Next step LGAD structures:

- Complete characterization with single strip measurements. **Probe card needed and ordered.**
- Bonding the NO LGAD and one between # 3 and # 5 structure to DAMPE readout hybrid (64 channels). We have the substrate; it needs to be populated with components and the chip. **Order in progress**
- **test the device both in laboratory (β , α) than in a beam with protons, somewhere beginning next year.**
- check possibility to thin structures down to 70 μm . If possible, proceed and then bond to another hybrid two differently thinned structure. Test them.



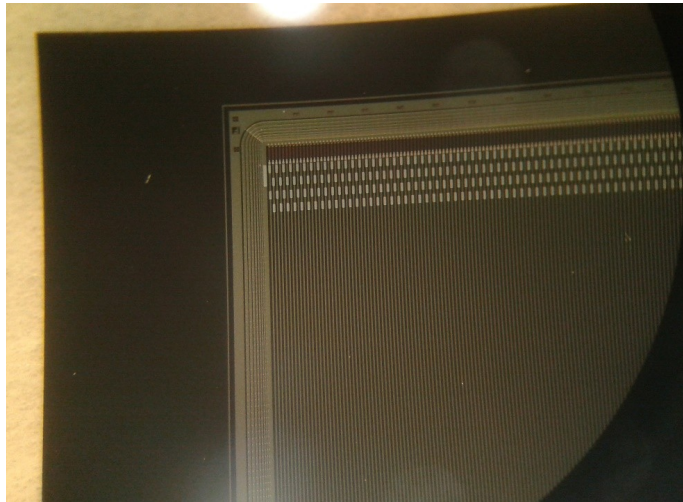
HW activities NON LGAD structures:

- We have obtained (no cost) two single sided test structures from Micron Semiconductor (UK).
- Dimensions: Thickness $150 \mu\text{m}$
Area: $99.410 \text{ mm} \times 95.715 \text{ mm}$
Mechanical edges: 4 mm parallel on strips and 2 mm perpendicular to strips
Pitch: $94 \mu\text{m}$, even (odd) pitch: $185 \mu\text{m}$
Nr of strips 1024, divided in 1024 left and 1024 right side.

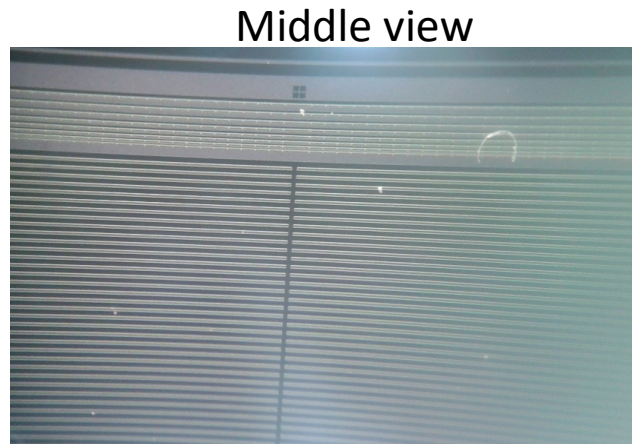




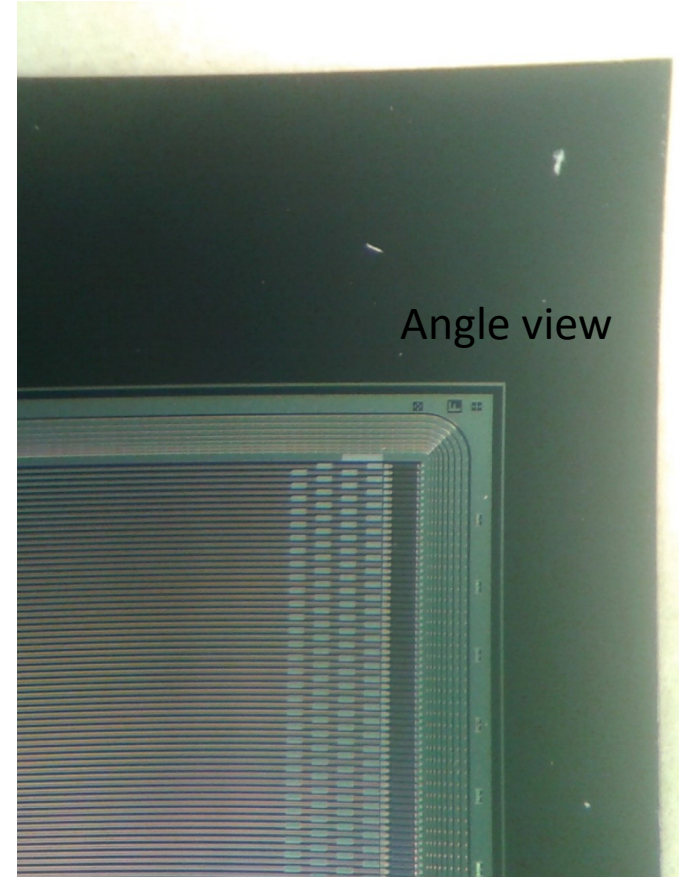
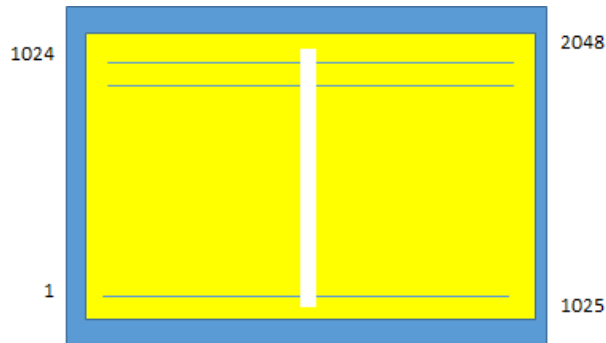
HW NON LGAD structures:



Angle view



Middle view

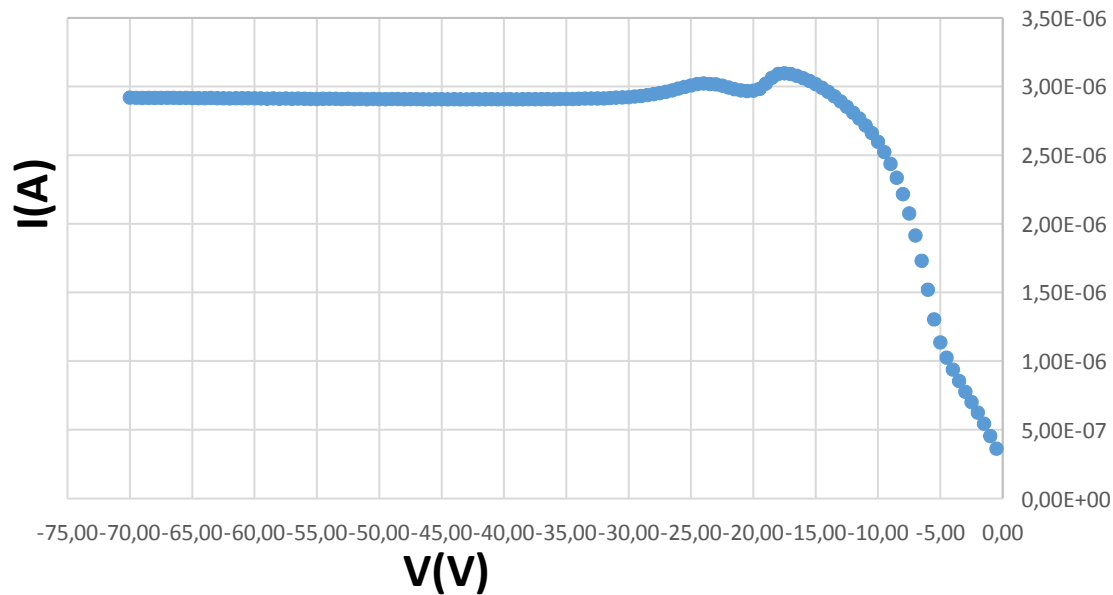


Angle view

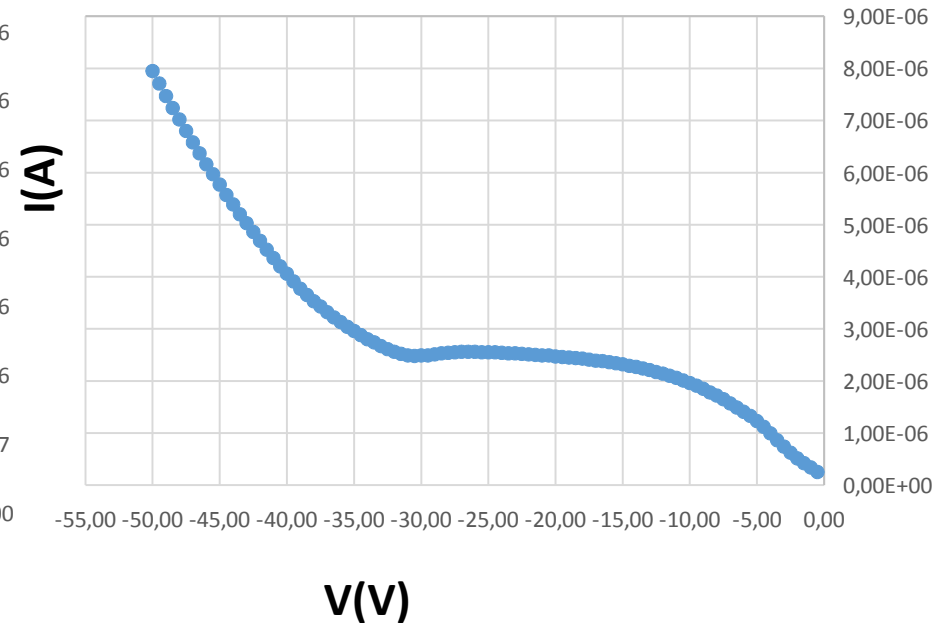


HW activities NON LGAD structures:

Micron 11



Micron 6



IV measurement: PA200, 07/11/2017

F. Moscatelli, M. Ionica

Bias NEGATIVE on back, P sensor

Probe on the innermost guard ring

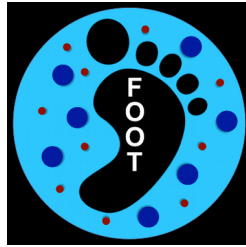
Micron 11 no problem up to $0.5 \text{ V}/\mu\text{m}$

Micron 6 develop breakdown @ $0.25 \text{ V}/\mu\text{m}$



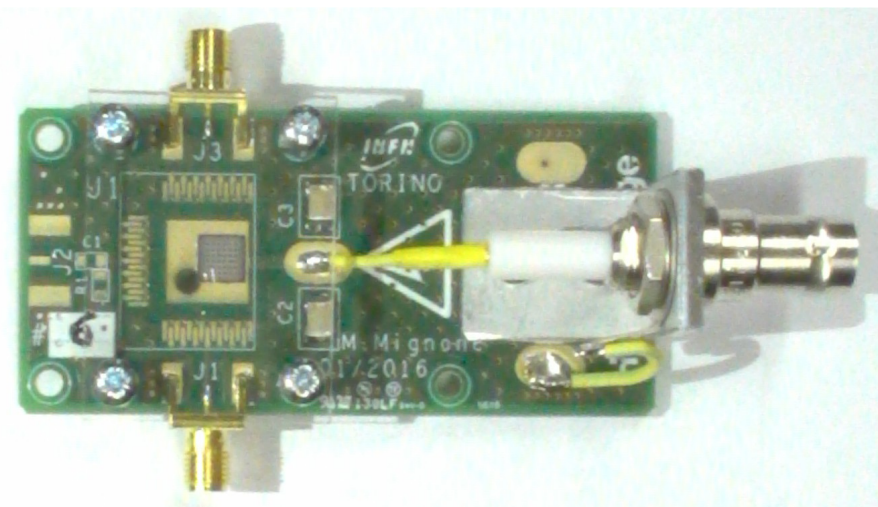
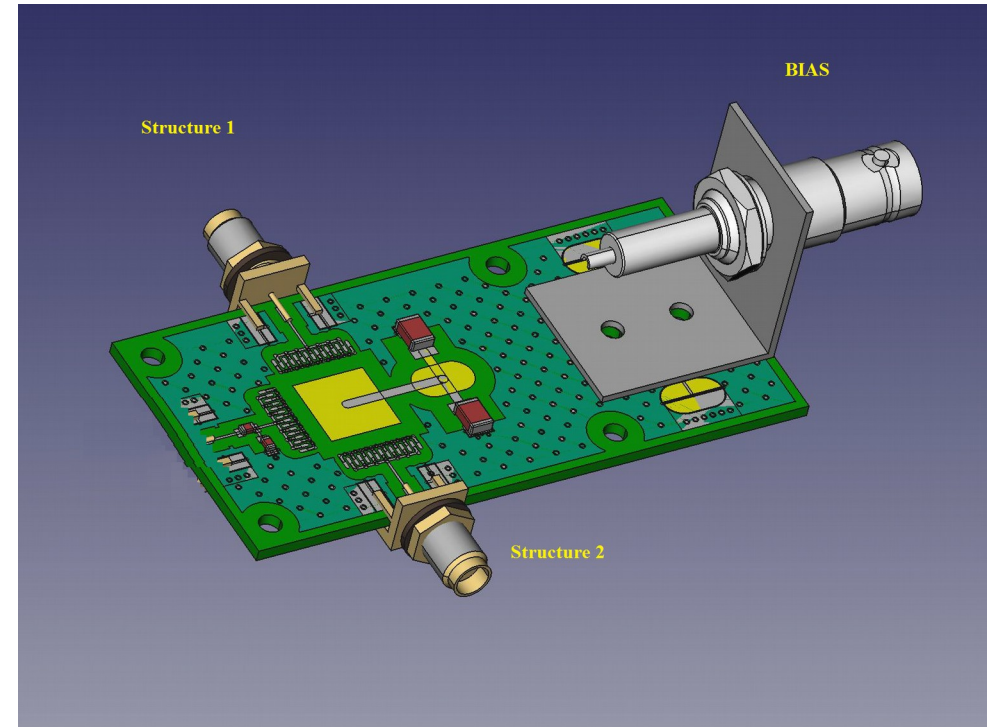
Next step NON LGAD structures:

- Bonding the Micron 11 sensor to one DAMPE readout hybrid (64 channels). We have the substrate, it needs to be populated with components and the chip. **Order in progress**
- **test the device both in laboratory (β , α) than in a beam with protons, somewhere beginning next year.**
- check possibility to have double sided sensors, same area.

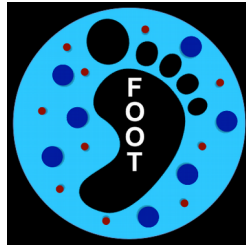


Analisis activities LGAD structures:

- We have tested two devices from Nicolò Cartiglia in LNS july ion beam test;
- each one has two $1 \times 1 \text{ mm}^2$ identical LGAD structures, $300 \mu\text{m}$ thick.



- goal to understand behaviour when ion beams hit the LGAD.

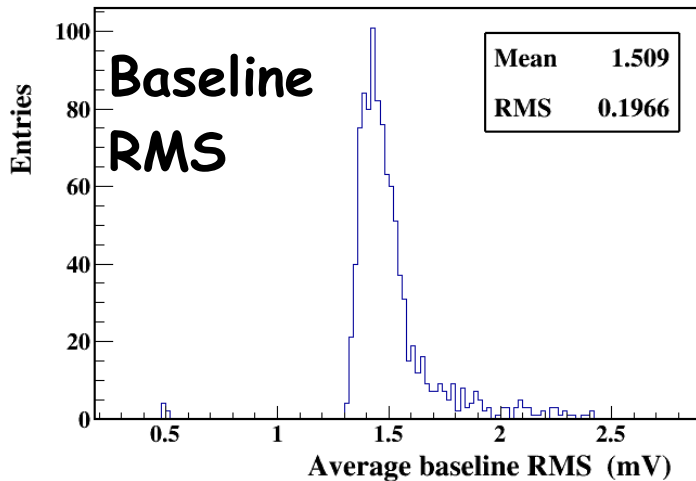
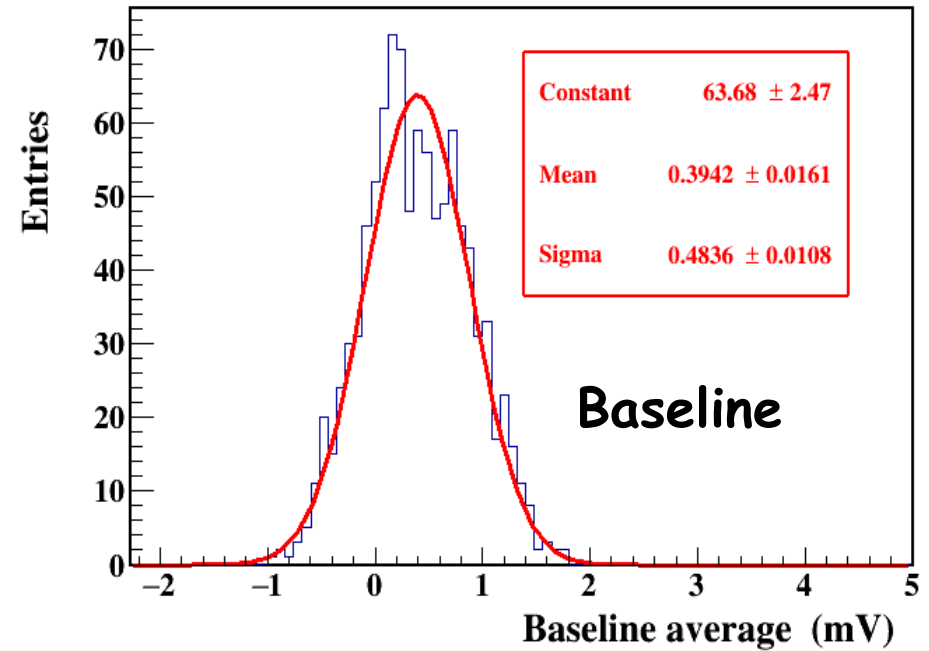
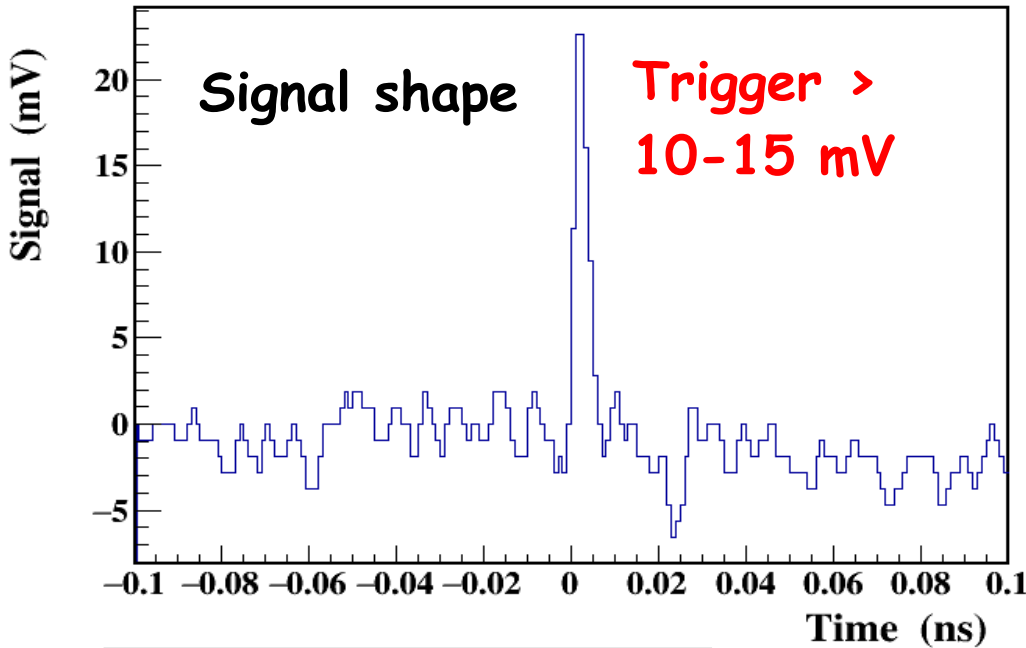


The devices have been exposed to the following ion beams (one structure at a time is read out, after 36 dB amplification by a CAEN wideband A1423 Amplifier, by a PicoQuant Oscilloscope).

$$1 \text{ mV} * 1 \text{ ns} / 50 \Omega / 63 = 0.317 \text{ fC} = 1671 e^-$$

- protons @ 77 MeV (Device A, structures 1 e 2)
- Helium @ 80 MeV (Device B, structures 3 e 4)
- **Carbon @ 80 MeV (Device B, structures 3 e 4) (Problems!)**
- Deuterium @ 80 MeV (Device B, structures 3 e 4)

For each ion beam a bias scan has been done, [-100 V, -800 V]. For each scan point 1000 triggers have been acquired (threshold varying from 10 to 15 mV).



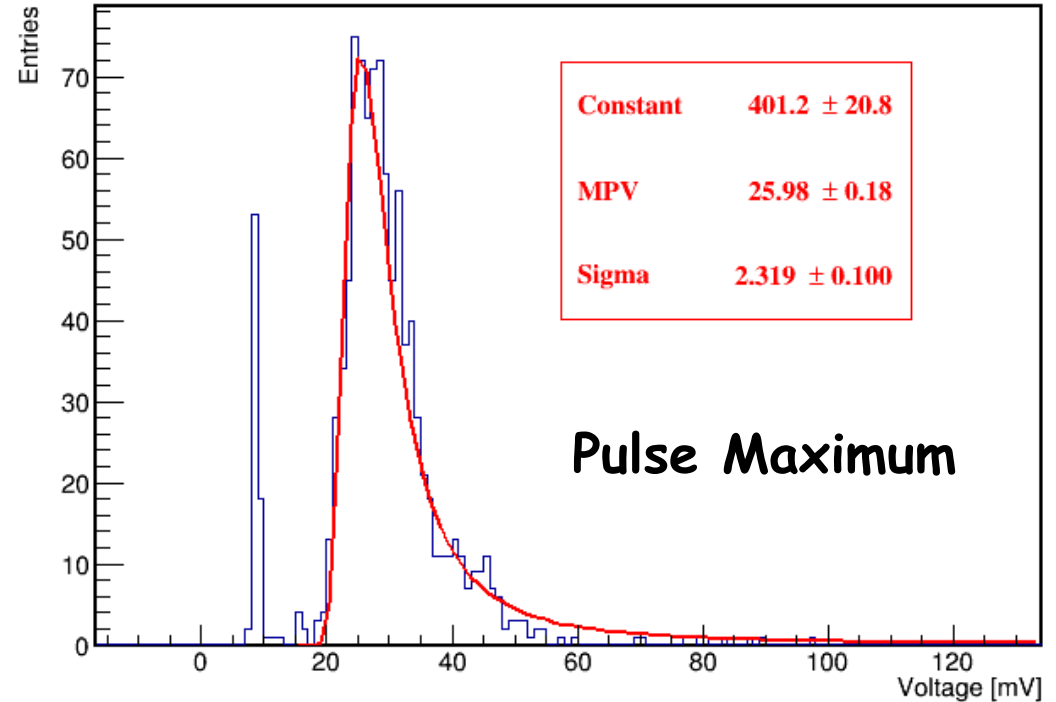
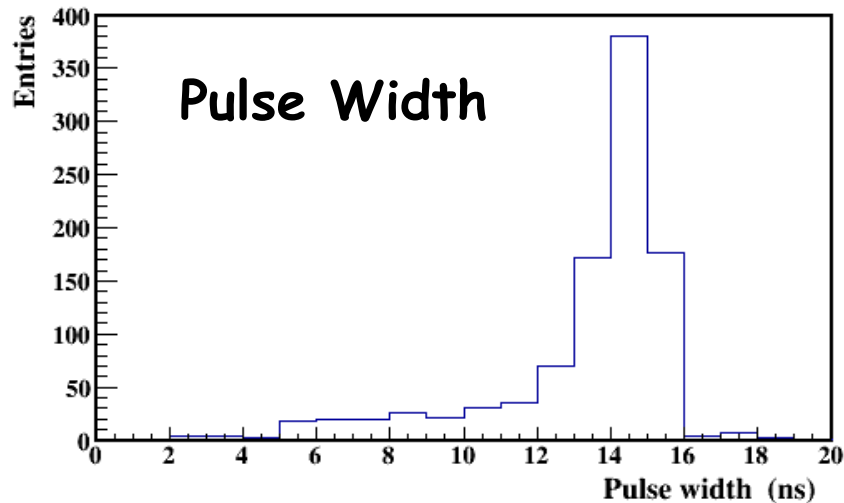
Baseline fluctuations (computed over the time segment preceding the trigger) are below 2 mV.

In analysis baseline subtracted from signal on event by event basis.

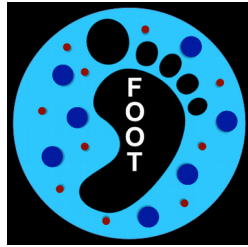


Variables to be measured:

- Pulse maximum;
- Pulse width;
- Pulse integral;
- Signal shape;

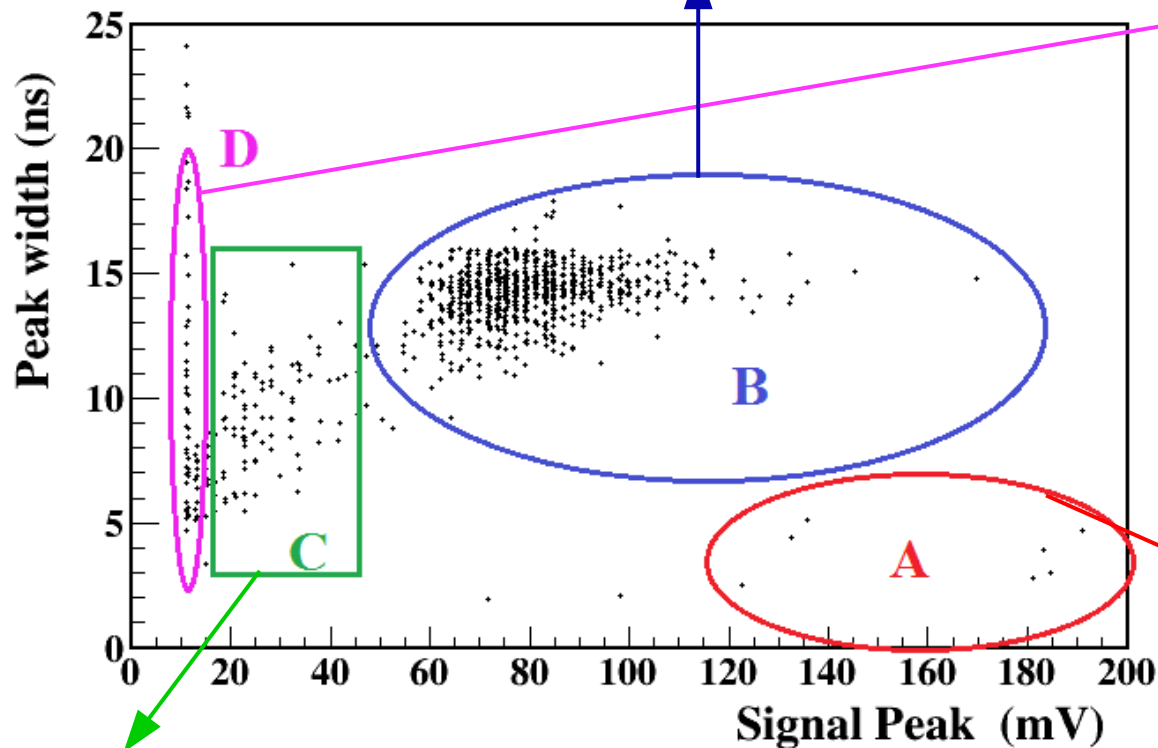


There are some queues for both distributions toward low values.
We studied the correlation.



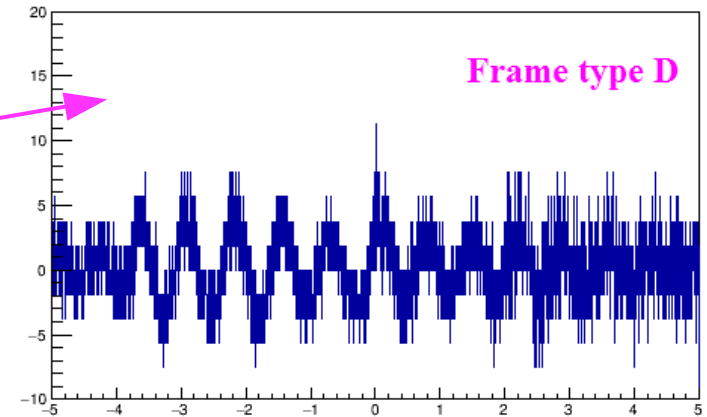
Several correlation regions:

Normal signal frame:

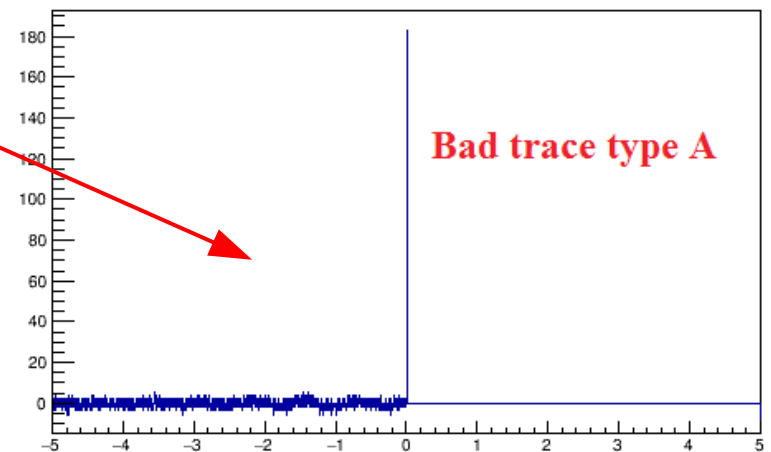


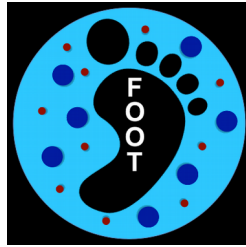
Low peak values:
incomplete charge
generation?

Near threshold frame:



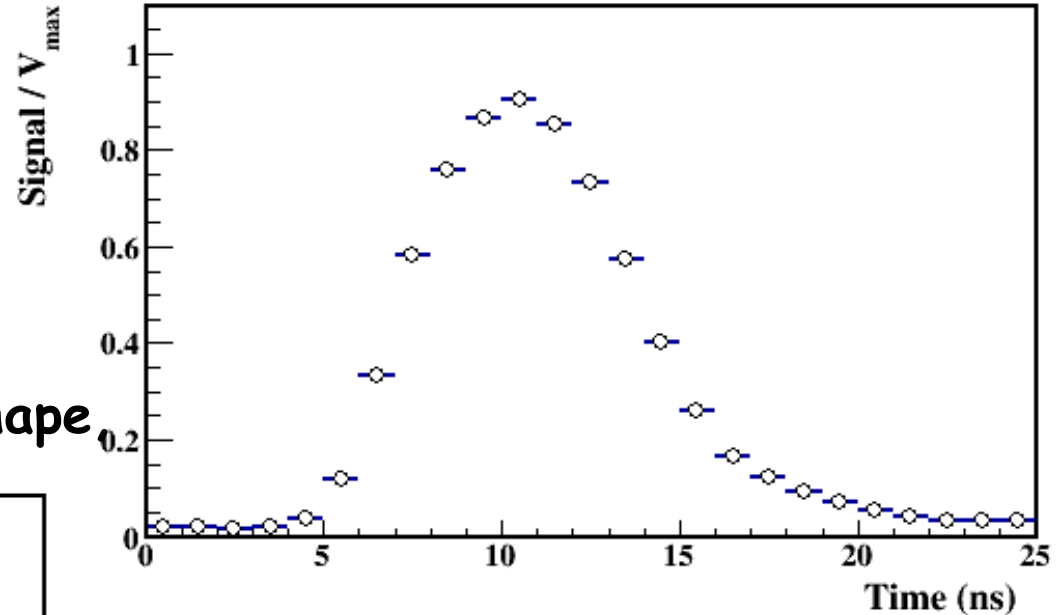
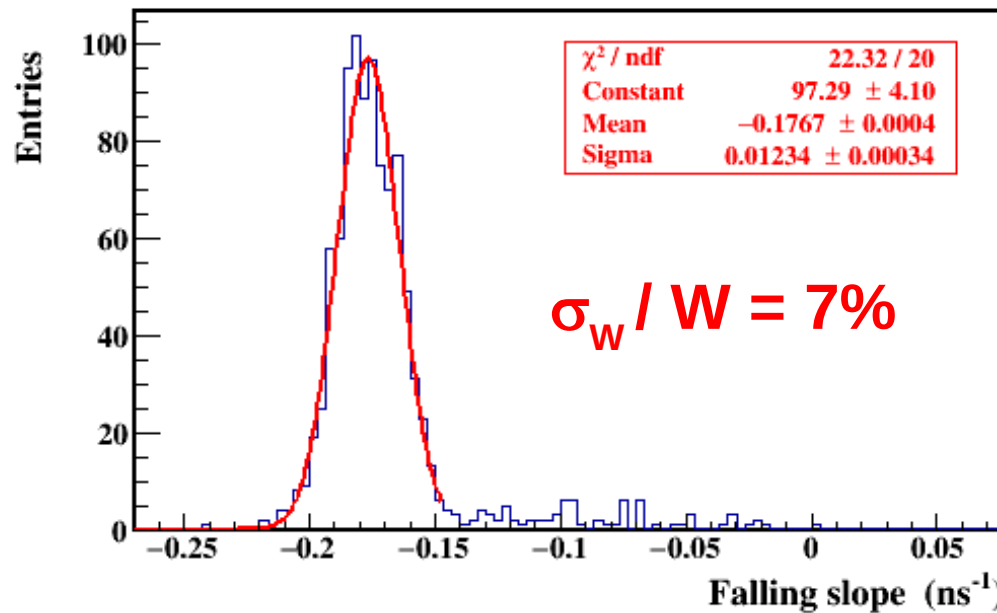
Low width frame:





Signal shape:

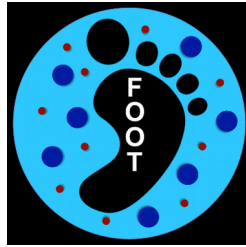
- Normalization to maximum signal value;
- Profile histogram: well defined shape



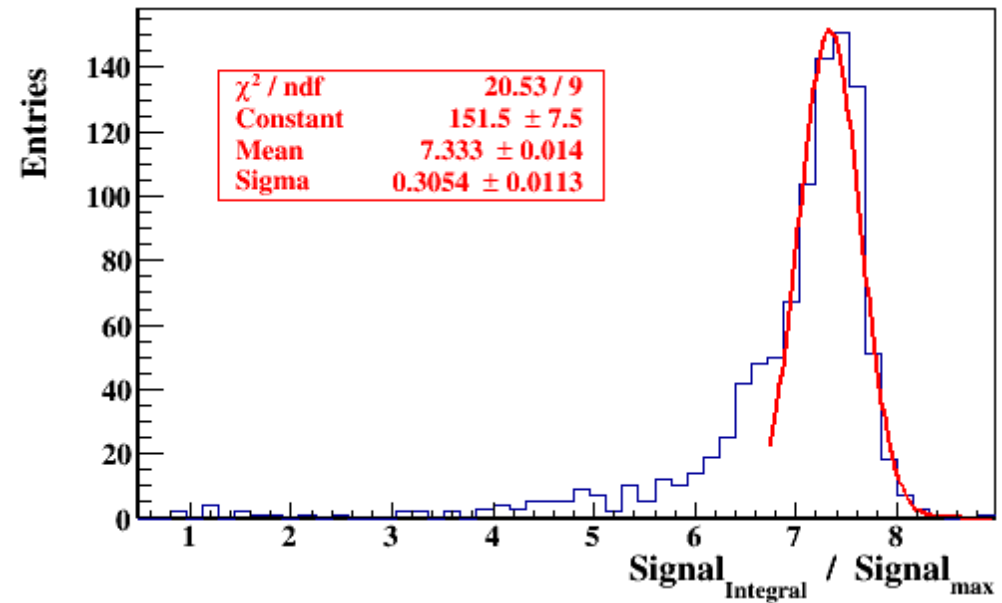
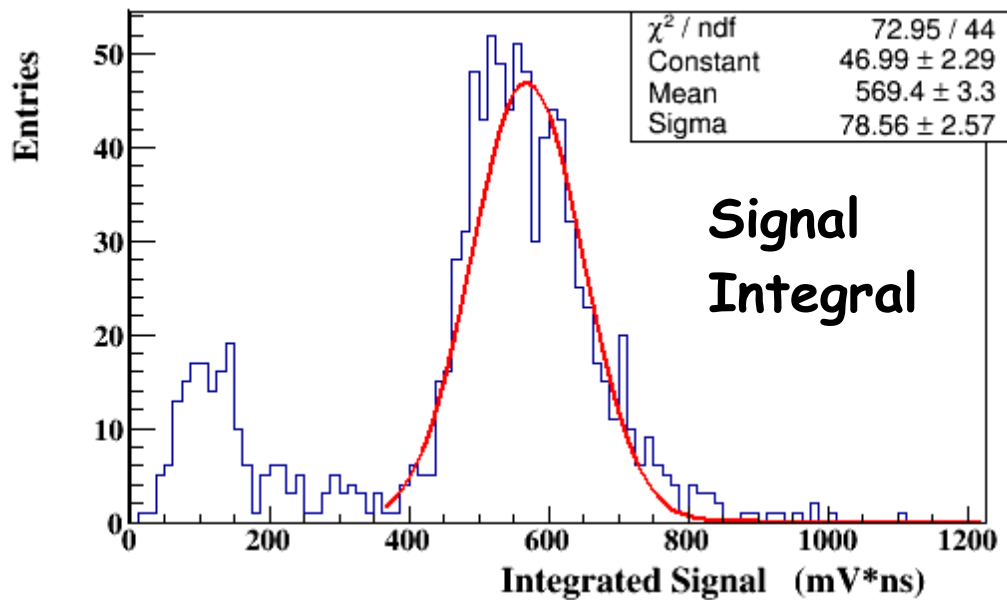
Both rising and falling times, due to filters on device board, are well defined. For example, falling part, computed for each frame, has a narrow distribution:

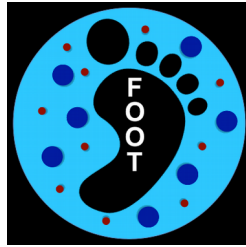
$$\text{Slope}^+ = -0.181 \pm 0.012 \text{ mV/ns}$$

$$\text{Slope}^- = -0.177 \pm 0.012 \text{ mV/ns}$$

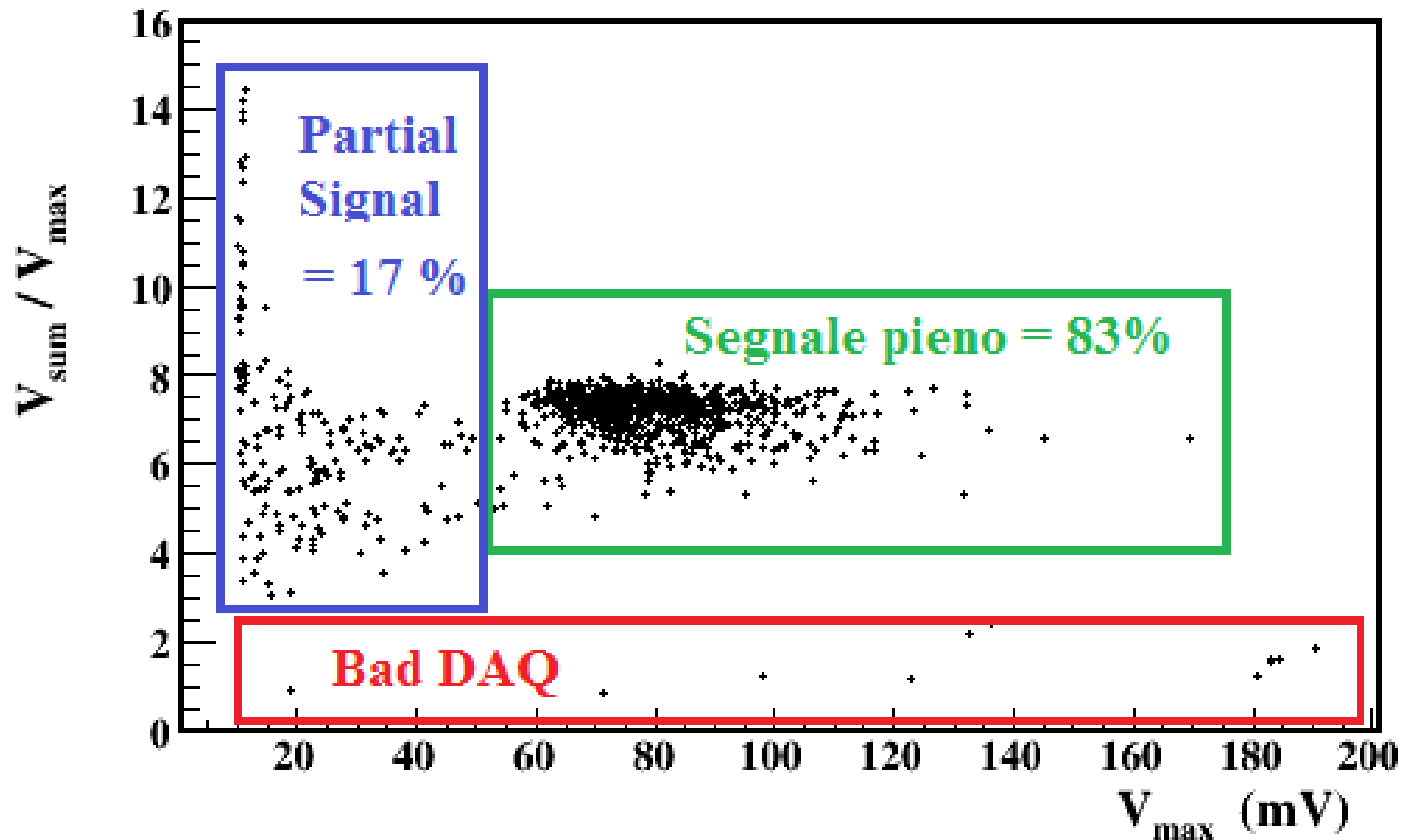


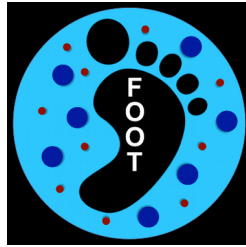
The pulse integral ($\text{Signal}_{\text{Integral}}$) is defined as the area integrated over time when $\text{signal} > \text{threshold}$. As threshold we have chosen 5 mV. Given the narrow distribution of both $\text{Signal}_{\text{Max}}$ and $\text{Signal}_{\text{width}}$, we do expect also a narrow distribution of this variable, and of rate with $\text{Signal}_{\text{Max}}$:





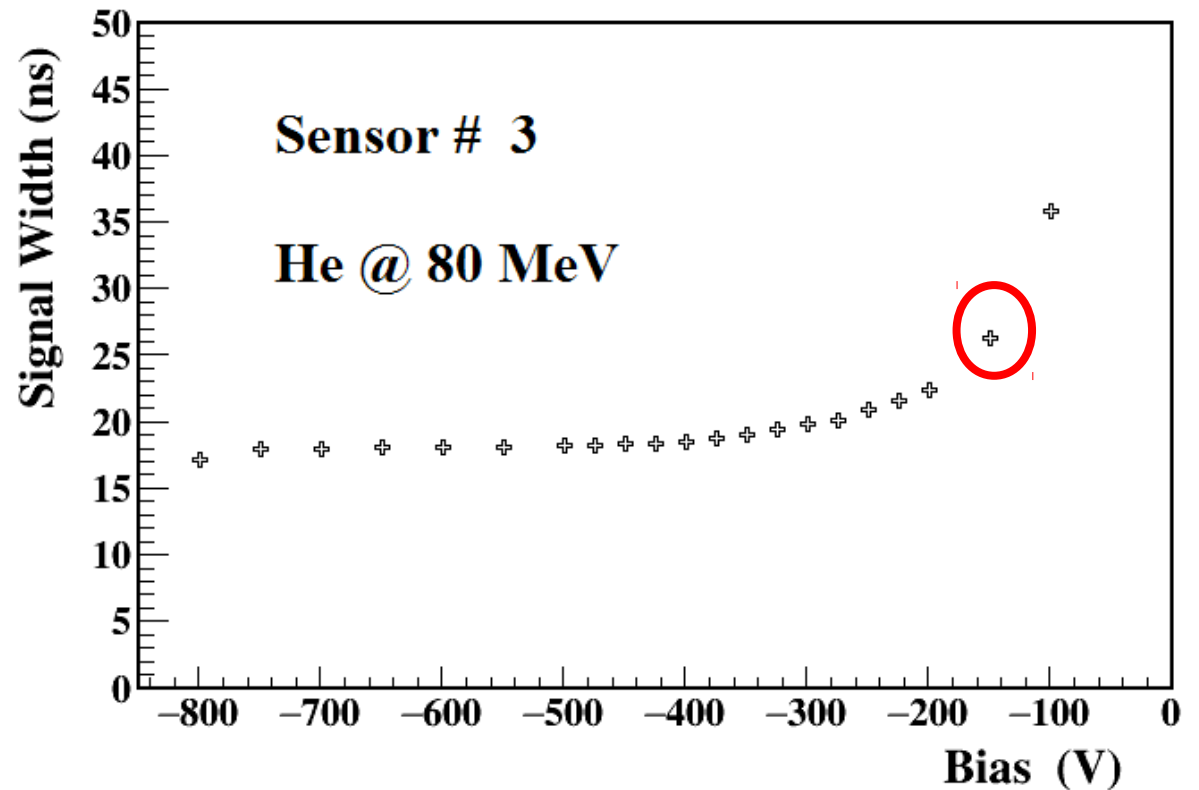
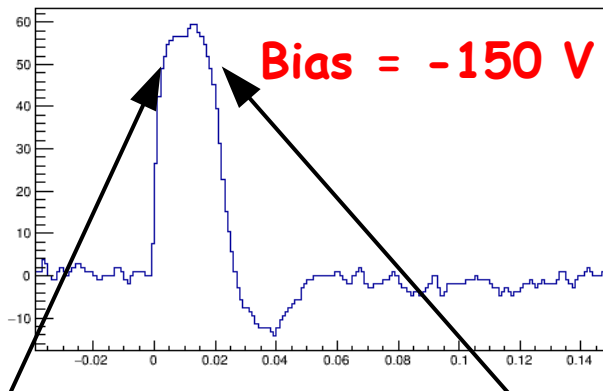
Finally, using the correlation plot between V_{\max} and rate, the **fraction of “good events”**, meaning with full charge collection **is of the order of 80%**





Width depends weakly on bias for most of the bias scan interval.

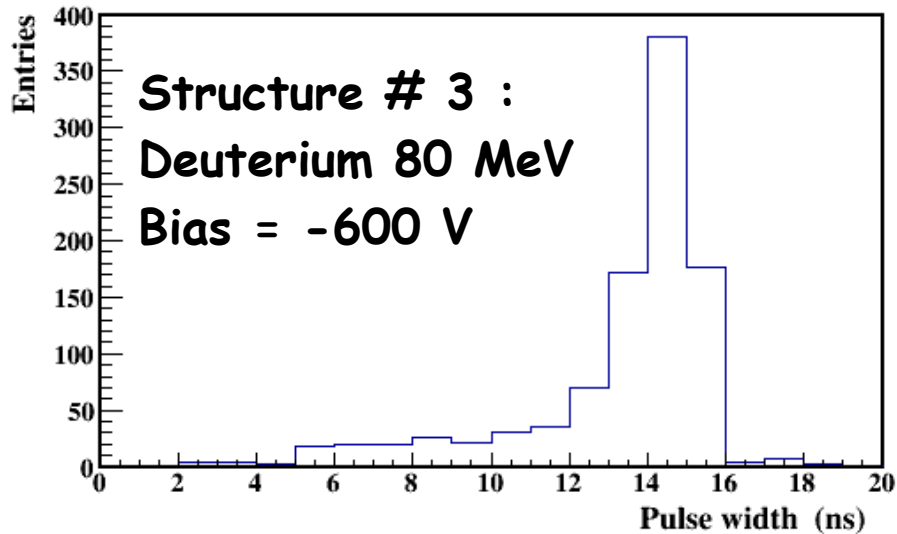
Only at low bias values there is a sizeable increase of the width:



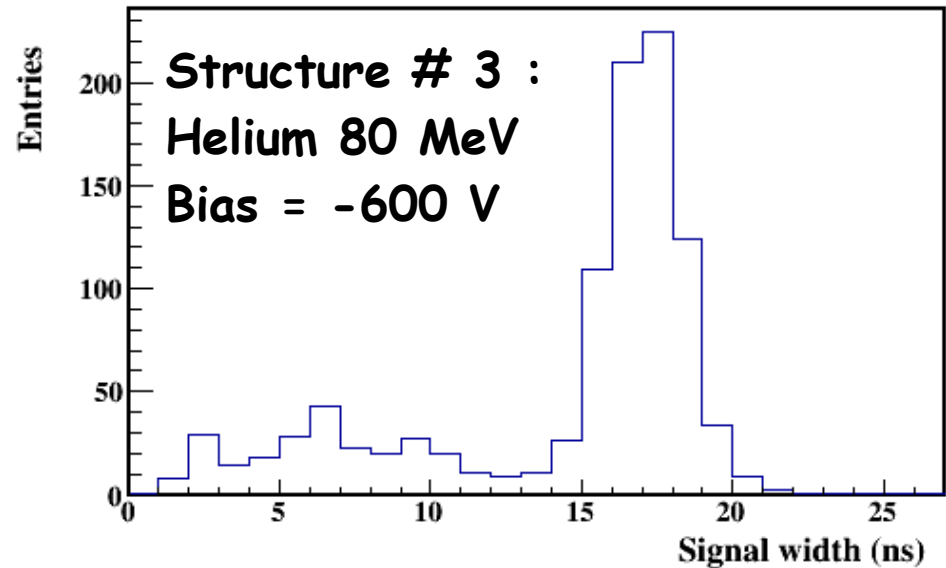
There is a kind of double peak.



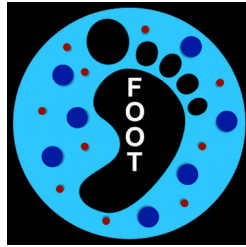
Width depends weakly on ion species because of higher ionization
→ longer time to fall below fixed threshold.



$$\langle \text{Width} \rangle_D = 14 \pm 1 \text{ ns}$$



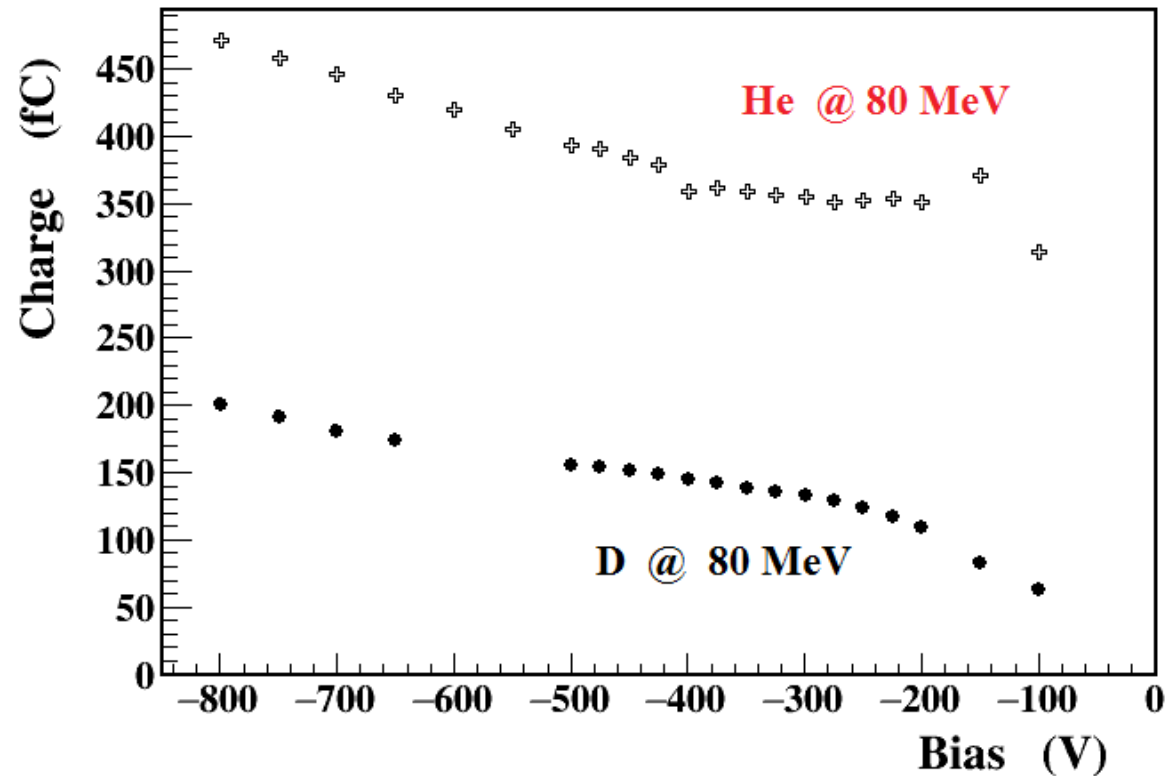
$$\langle \text{Width} \rangle_{\text{He}} = 16.5 \pm 1.5 \text{ ns}$$



Integrated signal (charge) depends on bias.

It increases quite linearly after -400 V.

Comparing with the signal of an 80 MeV proton in 300 μ thick silicon sensor at fully depleted bias



$$300 \mu\text{m} * 1600 \text{ eV} / \mu\text{m} / 3.6 \text{ eV} * 1.9 \cdot 10^{-19} \text{ C} = 24000 \text{ e}^- \sim 25 \text{ fC}$$

$$\text{Hence a gain @ } -650 \text{ V} : 173 \text{ fC} / 25 \text{ fC} = 6.9$$



Analisis still going on...

- ratio between He and Deuterium charge is not 4 (actually < 3)
[saturation? Non-linearity in charge multiplication mechanism?]
- shape of signal when bias is changing (more accurate description)
- dependence of results from 5 mV threshold choice.
- uniformity among several structures

Further measurement in lab with electrons and alfa sources.

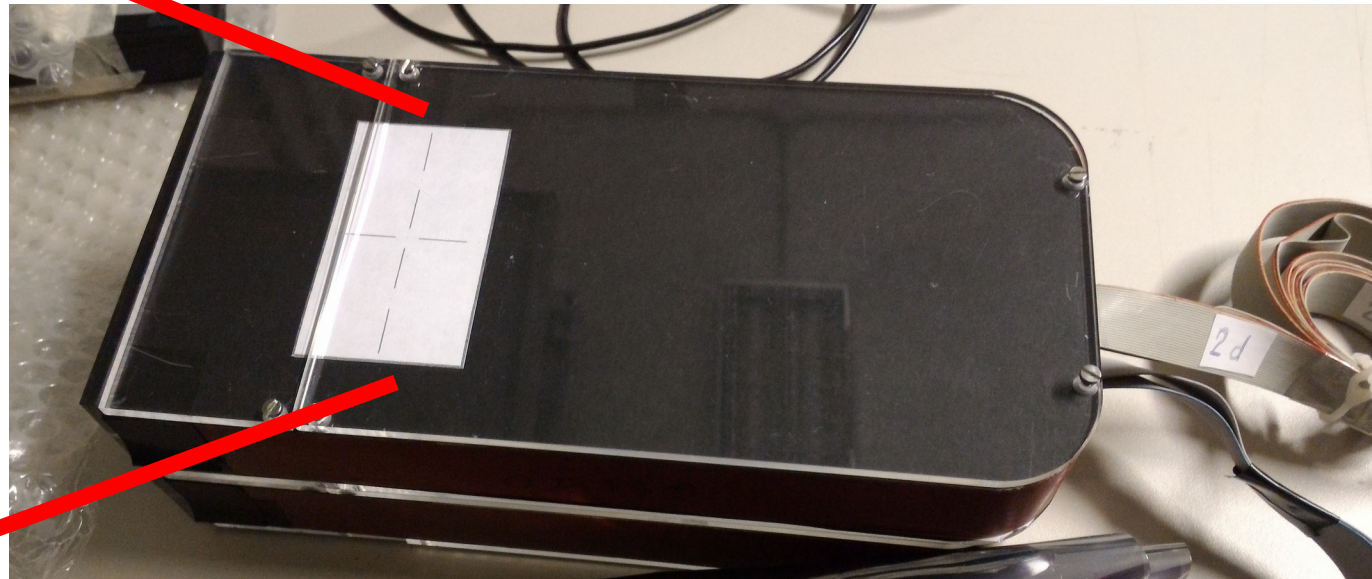
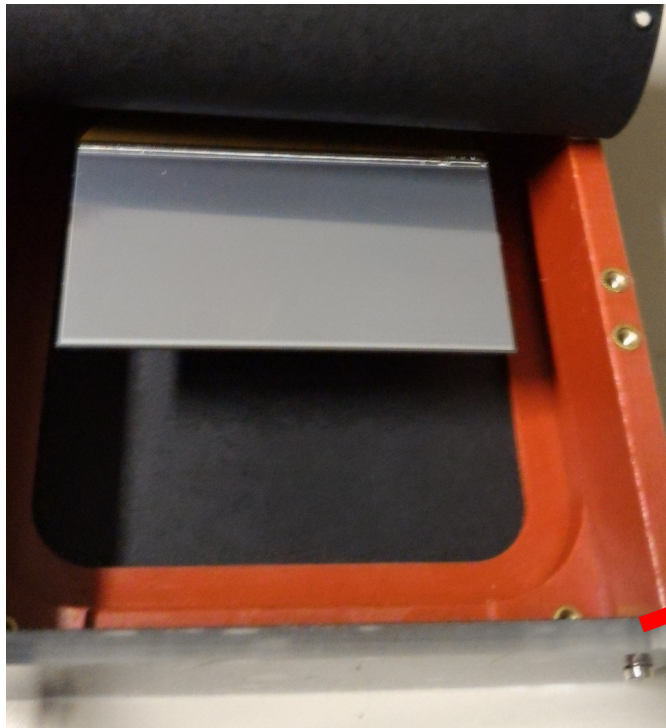
Measurements with monochromatic fluorescence photons.



Analisis activities Microstrip @ LNS:

We have put on beam an AMS-like double sided detector:

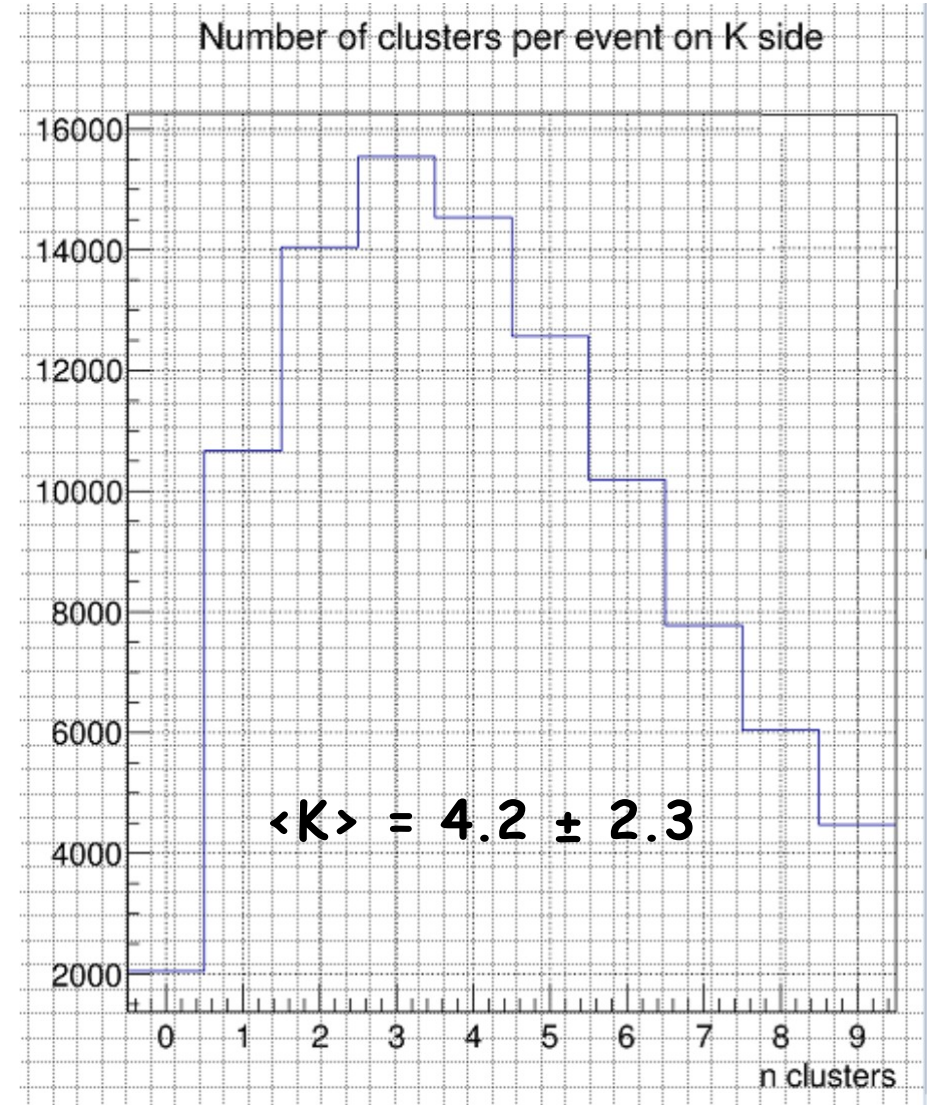
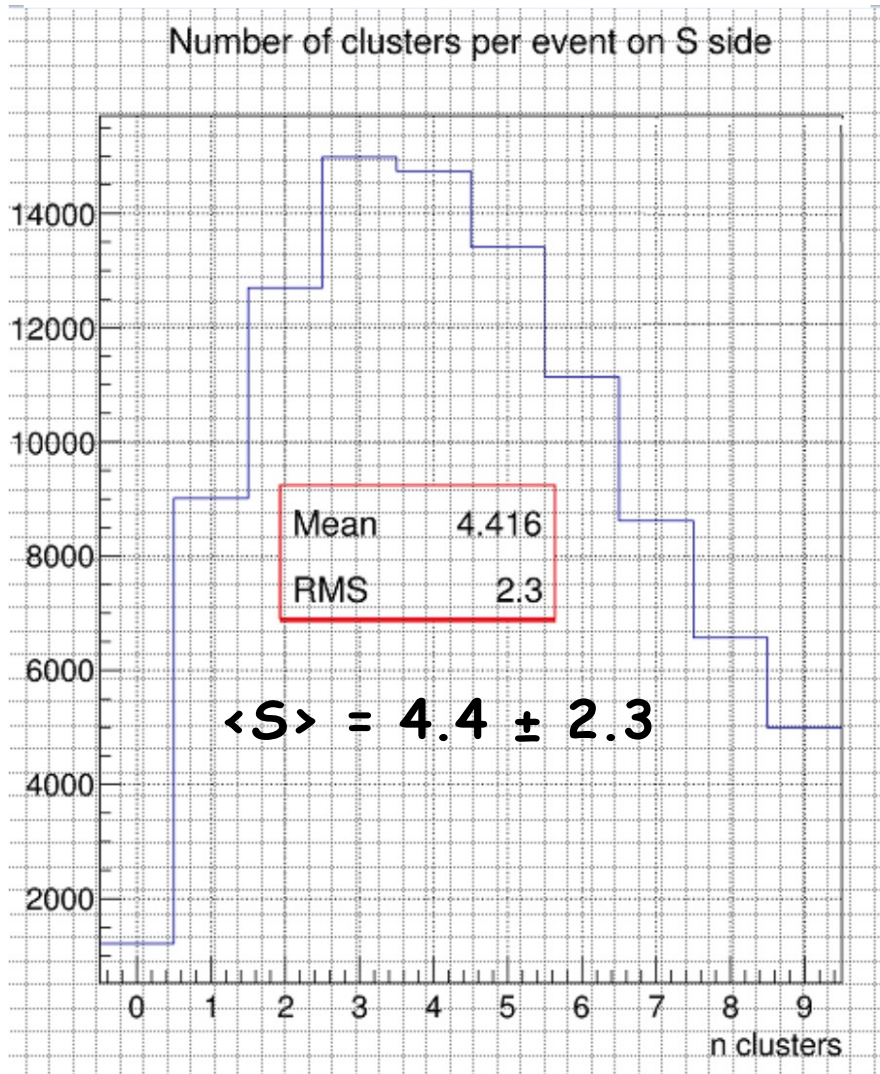
- with 320 μm thickness, 110 μm S-side, 107 μm K-side strip pitch.
- dimensions: $(640 \times 110 \mu\text{m}) \times (384 \times 107 \mu\text{m}) = 70.4 \times 41.1 \text{ mm}$;

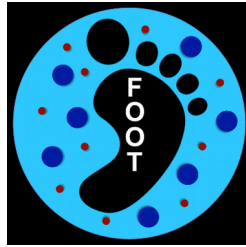




Preliminary Results

Deuterium @ 80



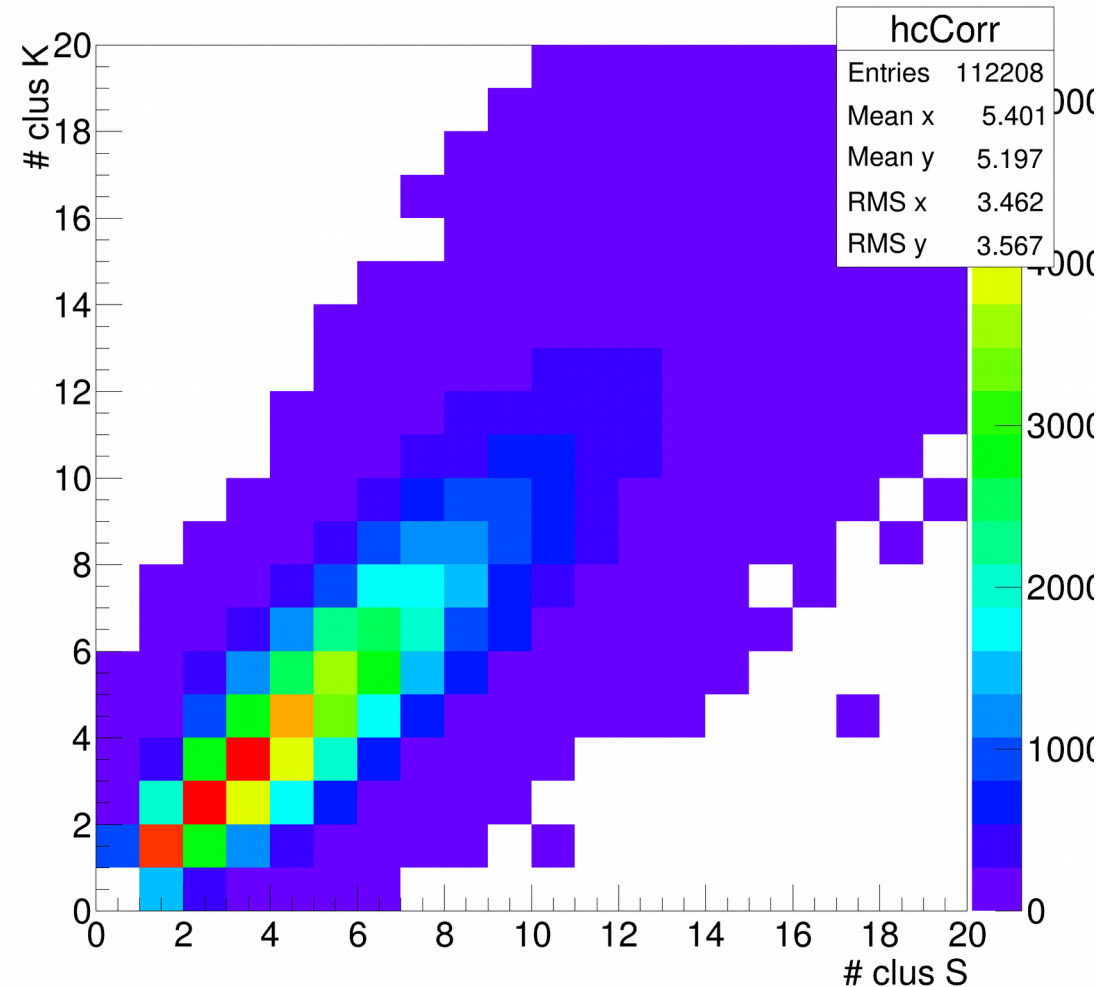


Number of clusters seen on both sides is closely correlated, even if there is a wide distribution around the correlation line.

Most likely due to inefficiencies on one or the other side, like dead or noisy strips.

Ongoing investigation

Cluster correlation





Beam profile:

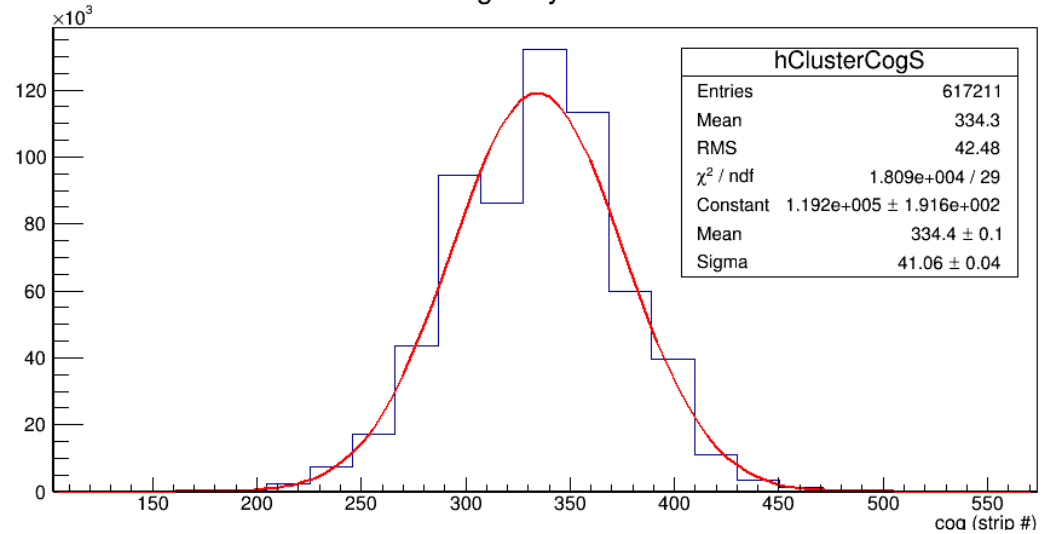
Side S:

$\sigma = 41$ strip = 4.5 mm
 FWHM = 2,56 * σ = 11.5 mm

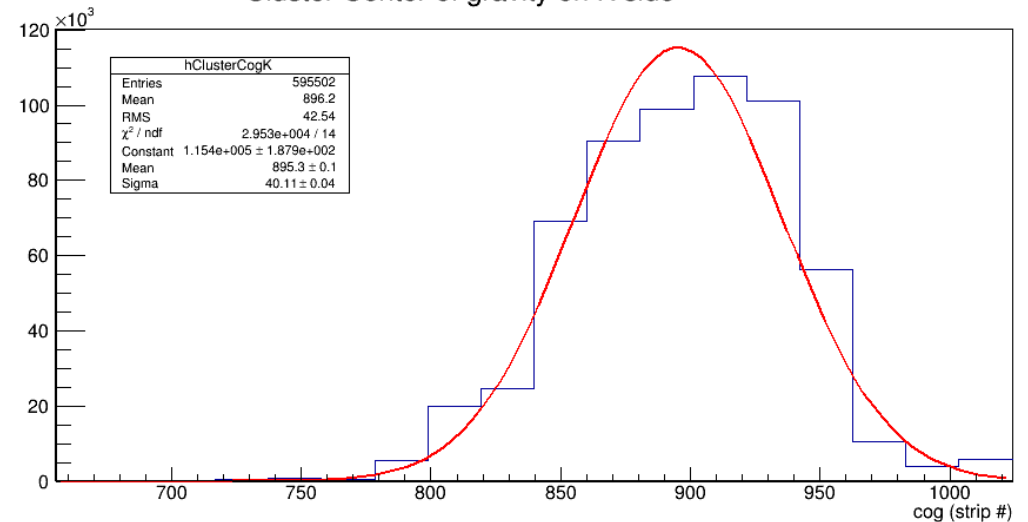
Side K:

$\sigma = 40$ strip = 4.3 mm
 FWHM = 2,56 * σ = 11.0 mm

Cluster Center of gravity on S side



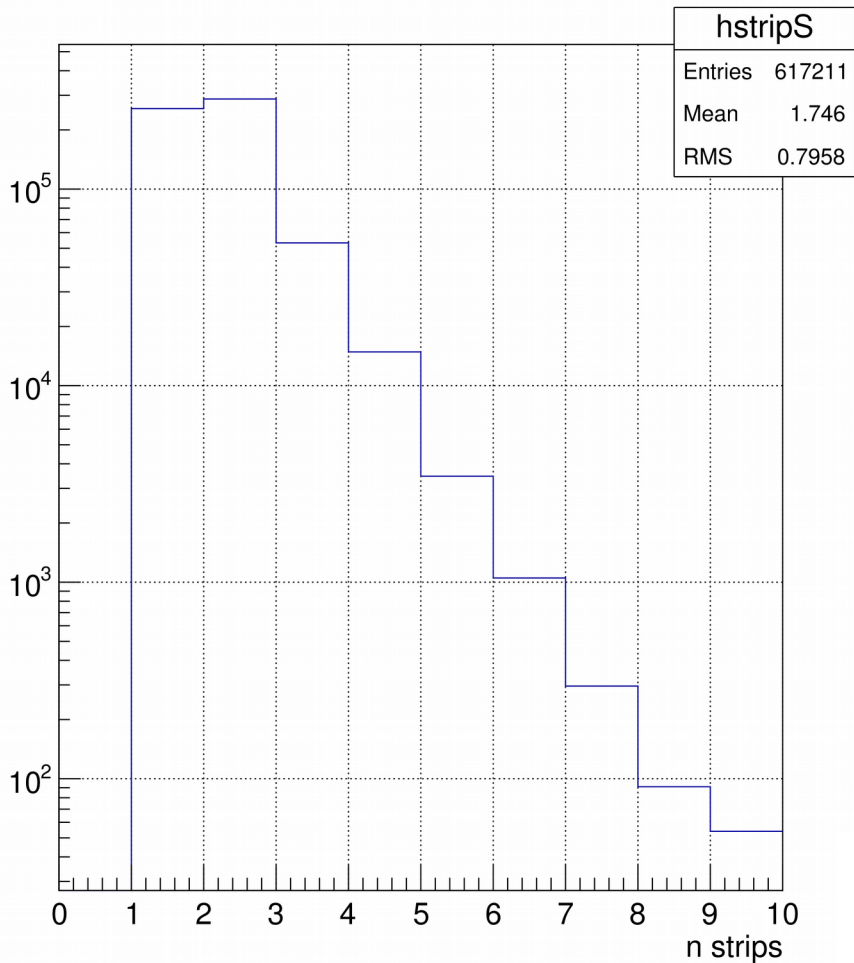
Cluster Center of gravity on K side



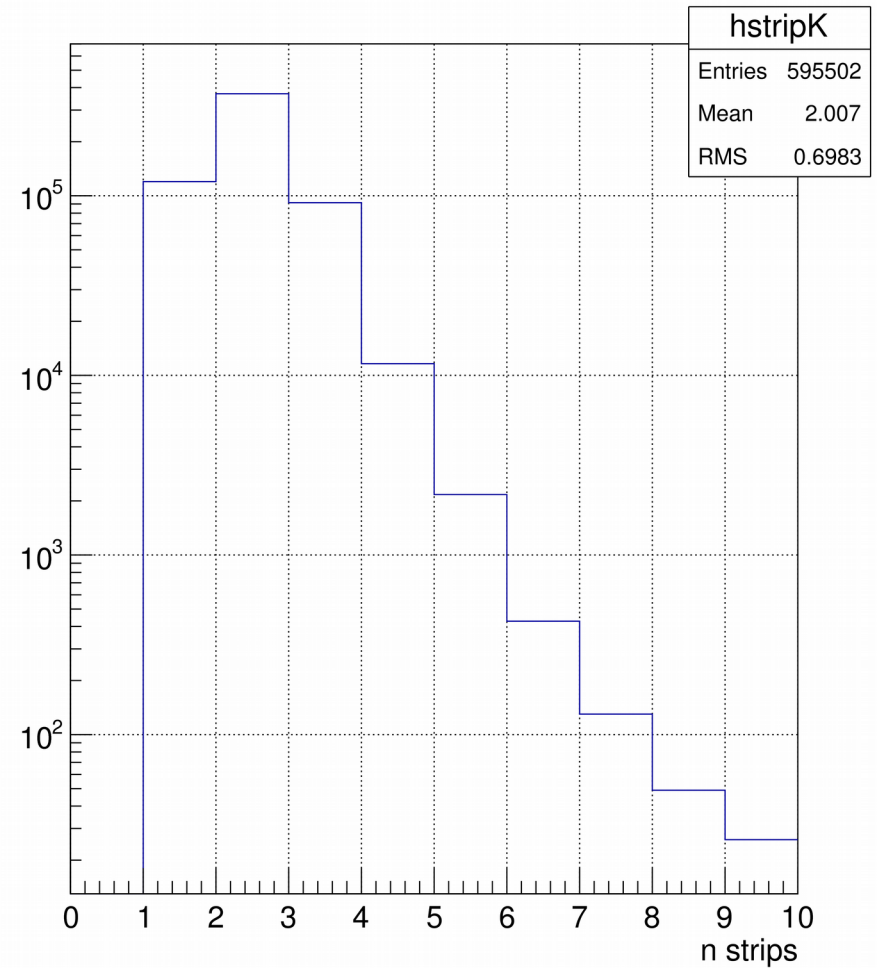


Number of strips in a cluster: very similar... $\langle S \rangle = 1.75$; $\langle K \rangle = 2.01$;

Number of strips per cluster on S side



Number of strip per cluster on K side

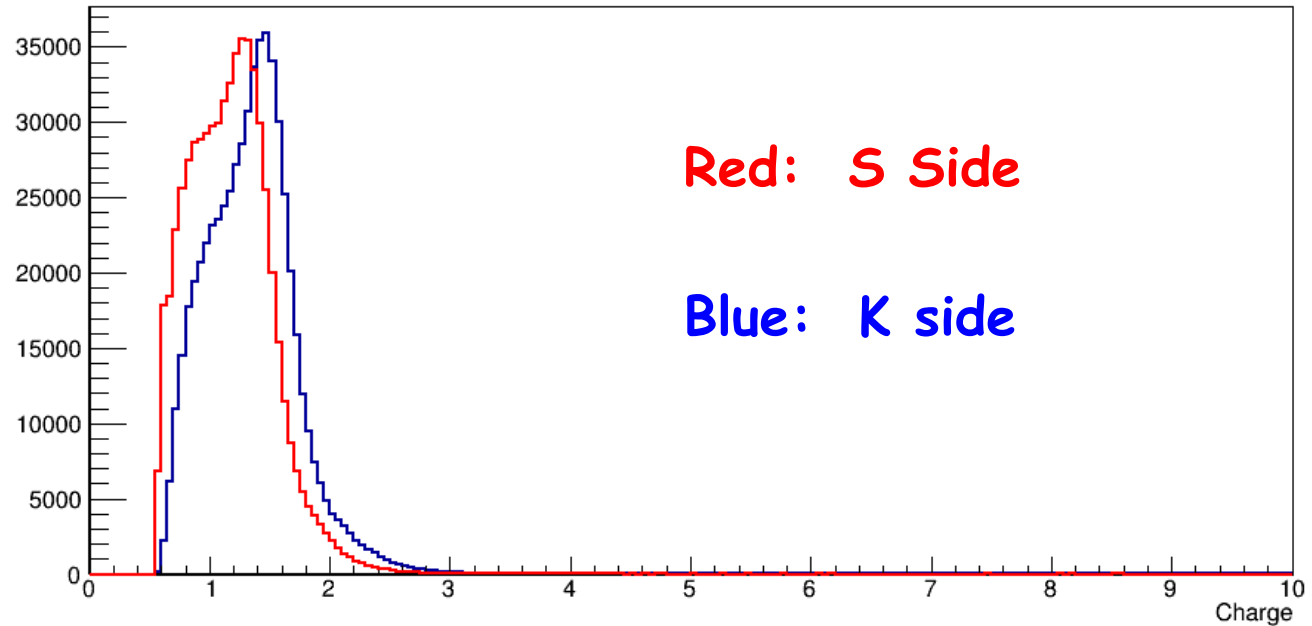




Cluster charge
normalized to 1 MIP:

$$1 \text{ MIP} = 320 \mu\text{m} * 80 \text{ e-h}/\mu\text{m} = 4.86 \text{ fC}$$

Cluster charge $\sim 7 \text{ fC}$



Seed charge / cluster charge = 65% $\sim 4.5 \text{ fC}$.

If for higher Z, signal scales as expected with Z^2 , for ^{16}O we should hence expect, rescaling for thickness: $64 * 4.5 * 150/320 = 135 \text{ fC}$



Cluster charge correlation between S and K side:

Only events with 1 cluster in S
and 1 in K have been selected.
A very good correlation is observed

The same amount of e-h is seen by
both sides.

This could be used to reject fake
hits and reduce combinatorial in
position reconstruction.

